

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V.  Name of Laboratory		BZX884-C68 Part Description						
Assembly reliability labs		MCD package						
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
# A1	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	113	9040	0		
# B1	HTRB High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	138	11040	0		
# B1b	SSOP Steady State Operational	MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current	1000 hours	20	1600	0		
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	28	2240	0		
# A3 alt	<b>AC</b> Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	28	2240	0		
# A2 alt	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage $^{[1]}$	1000 hours	28	2240	0		
# A5	<b>IOL</b> Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj = 100$ °C for 15000 cycles	1000 hours	29	2320	0		
# C8	<b>RSH</b> Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.		
# C10	<b>SD</b> Solderability	J-STD-002		63	630	0		

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11040	0	0.38	2.60E+09

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